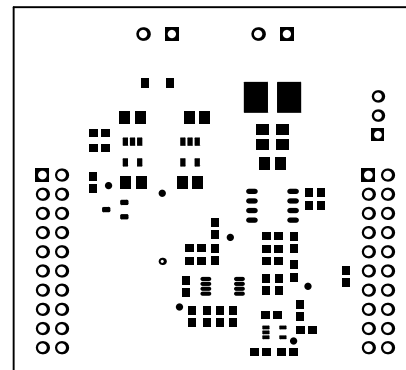
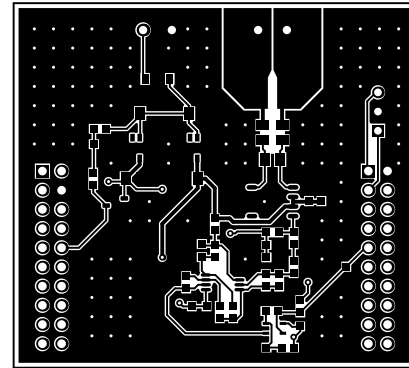


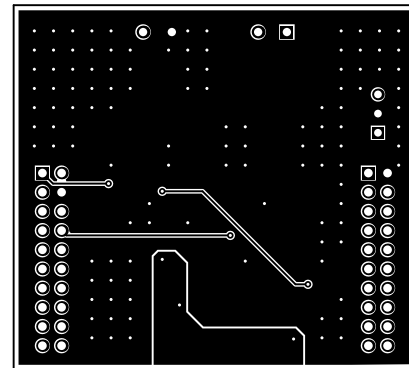
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01421	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01421		
PLOT NAME = Top Overlay	GENERATED : 6/28/2017 5:57:18 PM	TEXAS INSTRUMENTS	



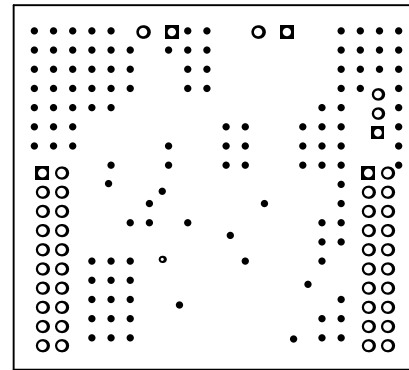
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01421	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01421		
PLOT NAME = Top Solder Mask	GENERATED : 6/28/2017 5:57:19 PM	TEXAS INSTRUMENTS	



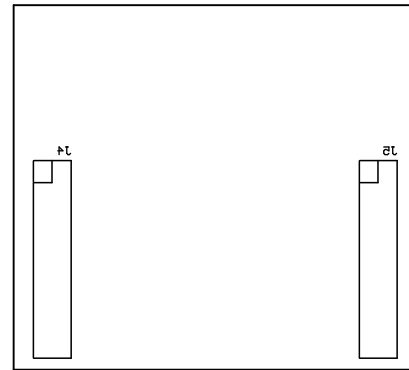
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01421	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01421		
PLOT NAME = Top Layer	GENERATED : 6/28/2017 5:57:20 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01421	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01421		
PLOT NAME = Bottom Layer	GENERATED : 6/28/2017 5:57:21 PM	TEXAS INSTRUMENTS	

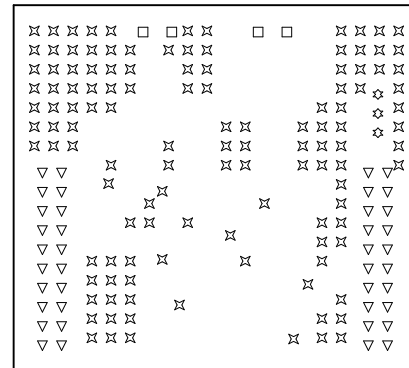


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01421	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01421		
PLOT NAME = Bottom Solder Mask	GENERATED : 6/28/2017 5:57:22 PM	TEXAS INSTRUMENTS	

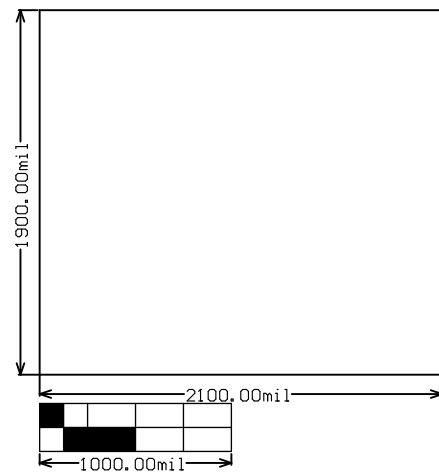


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01421	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01421		
PLOT NAME = Bottom Overlay	GENERATED : 6/28/2017 5:57:24 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
✕	122	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
✱	3	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
□	4	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	
▽	40	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	
	169 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01421	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01421		
PLOT NAME = Drill Drawing	GENERATED : 6/28/2017 5:57:25 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01421	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01421		
PLOT NAME = Board Dimensions	GENERATED : 6/28/2017 5:57:26 PM	TEXAS INSTRUMENTS	



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